

**EXPEDITED PROCEDURE - EXAMINING GROUP 2815** 

#8/#MC/C

S/N 09/826,661

**PATENT** 

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Yong-Jun Hu

Examiner: Joseph Nguyen

Serial No.:

09/826,661

Group Art Unit: 2815

Filed:

April 5, 2001

Docket: 303.098US4

Title:

LOW ANGLE, LOW ENERGY PHYSICAL VAPOR DEPOSITION OF

**ALLOYS** 

File: 444880.WPD

## **AMENDMENT & RESPONSE UNDER 37 C.F.R. § 1.116**

Box AF Commissioner for Patents Washington, D.C. 20231

In response to the final Office Action mailed April 24, 2002, please amend the application as follows.

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## In the Claims

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect cancellation of claims 31-37, 39-47, and 55-70, and addition of new claims 71-107. Specific amendments to individual claims are detailed in the following marked-up set of claims.

## Please add the following new claims:

71. In a semiconductor device having a substrate, a contact hole in a layer of insulator material directly overlying the substrate, the hole comprising:

a bottom surface having at least one generally planar layer of conductive material including at least two different constituent elements; and

a vertical sidewall consisting substantially entirely of the aforementioned layer of insulator material.

72. The device of claim 71 where the planar layer contacts the lower end of the sidewall.

08/27/2002 AWONDAF1 00000021 09826661

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